AMENDMENTS TO THE CLAIMS

1. (currently amended) A dicing/die bonding adhesion tape comprising a substrate, a silicone adhesive layer directly on the substrate, which silicone adhesive layer is formed by heat curing a silicone adhesive composition comprising a heat curable chain-like organopolysiloxane and a solid silicone resin, and a bonding layer directly on the silicone adhesive layer, wherein

the tack strength between the silicone adhesive layer and the bonding layer is 0.2 to 2.0 N/25 mm, and

said bonding layer is formed of an bonding composition comprising (A) a polyimide resin, (B) an epoxy resin, and (C) an epoxy resin curing catalyst.

2. (original) The adhesion tape of claim 1, wherein the substrate is an extensible film.

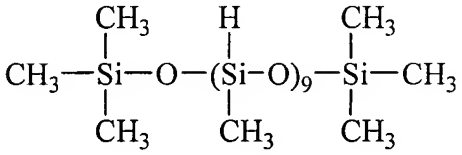
3. (original) The adhesion tape of claim 2, wherein the extensible film is polyethylene or polypropylene.

4. (currently amended) The adhesion tape of claim 1, wherein the silicone adhesive composition is an organic peroxide curing type or a platinum addition curing type silicone adhesive composition ~~comprises a platinum addition curable or radiation curable silicone adhesive material~~.

5. (original) The adhesion tape of claim 1, wherein the polyimide resin (A) in the bonding composition has phenolic hydroxyl radicals on its polymer skeleton.

6. (original) The adhesion tape of claim 1, wherein the polyimide resin (A) in the bonding composition has a siloxane structure in its polymer skeleton.

7. (new) The adhesion tape of claim 1, wherein the silicone adhesive composition has the formula



8. (new) The adhesion tape of claim 1, wherein the tack strength between the silicone adhesive layer and the bonding layer is 0.32 to 1.8 N/25 mm.

9. (new) The adhesion tape of claim 1, wherein the bond strength ranges from 13 to 18 MPa.